

WHAT IS CLAIMED IS:

1. A resin-molded product having a thick portion and thin portion, wherein the thick portion is a foamed body.
- 5 2. The product according to claim 1, wherein the thick portion is a rod, and the thin portion is a plate.
3. The product according to claim 1, wherein the thick portion is a ring, and the thin portion is a cylinder.
- 10 4. A resin-molded product preparing method of preparing a resin-molded product having a thick portion and thin portion, wherein
after an inert gas is allowed to saturate into a resin material, the resin material is injected, for a
15 injection time of not more than 1 sec, into a metal mold at a temperature lower by 5°C to 25°C than a heat deformation temperature of the resin material before the inert gas saturates, and the resin material is
20 extracted from the mold after being foamed and hardened in the mold.
5. A resin-molded product preparing method of preparing a resin-molded product having a thick portion and thin portion, wherein
after an inert gas is allowed to saturate into a
25 resin material, the resin material is injected into a metal mold in which a mold portion for molding the thin portion has a thermal conductivity of 0.15 to 8.5 W/m·

K, and the resin material is molded in the metal mold.

6. The method according to claim 5, wherein the mold portion for molding the thin portion is made up of a resin layer having a thermal conductivity of 0.15 to 0.98 W/m·K at room temperature, and a hard coat layer.

7. The method according to claim 6, wherein the resin layer is a polyimide layer formed by vapor deposition polymerization and having a thickness of 0.05 to 0.5 mm.

8. The method according to claim 5, wherein the mold portion for molding the thin portion is made of a ceramic having a thermal conductivity of 1.4 to 1.9 W/m·K at room temperature.

9. The method according to claim 5, wherein the mold portion for molding the thin portion is made of a porous metal having a thermal conductivity of 3.5 to 8.5 W/m·K at room temperature.

10. The method according to claim 5, wherein a mold portion for molding the thick portion is made of a copper alloy or aluminum alloy having a thermal conductivity of 150 to 400 W/m·K at room temperature.

11. The method according to claim 5, wherein a mold portion for molding the thick portion is made of carbon steel having a thermal conductivity of 25 to 55 W/m·K at room temperature.

12. A resin-molded product preparing method of preparing a resin-molded product having a thick portion

and thin portion, wherein

after an inert gas is allowed to saturate into a resin material, the resin material is injected into a metal mold, and a holding pressure of 80 to 200 Mpa is
5 applied for 0.1 to 1 sec.